Closing Keynote Speaker Introduction

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Paul Werbaneth

Vice President - Marketing and Applications

Tegal

Tegal Corporation

Focused Innovation. Solid Results.

Tegal Mission:

To lead the market in innovative, specialized production solutions that enable manufacturers of MEMS and 3D microelectronics to achieve technical and manufacturing breakthroughs, and create sustainable value.

November 2010

Canon Marketing Japan: A Causeway to the Japanese Market

By Francoise von Trapp, 3D InCites, 01 November 2010

It's no secret that Japan has its own ideas of how to do pretty much everything. The culture is an interesting mix of ancient tradition, ceremony, modernization, and technological advancement. The centuries-old Imperial Palace and grounds, home to the sitting Emperor, is surrounded by the steel-and-glass cosmopolitan city of Tokyo. A complex, intricate, state-of-the-art public transportation system deposits Shinto worshipers almost at the entrance of the densely forested Meiji Shrine, a peaceful oasis for those who lead otherwise hectic lives. Conversely, a Japanese interpreter commutes 10K to a high tech assignment on a one-speed bicycle, on a humid, rainy morning.

http://www.semineedle.com/posting/91871?snc=20641

TSV Seminar Looks Back to the Future of Etch

By Francoise von Trapp, 3D InCites, 01 November 2010

Attending last week's TSV Seminar in Tokyo, hosted by Electronic Journal, posed a bit of a challenge as all but one presentation was in Japanese. However, thanks to the detailed diagrams and smatterings of English in the proceedings along with careful note taking by Tegal Corp.'s interpreter Yukumi Hayafune, I was able to summarize the main points of the event.

http://www.semineedle.com/posting/91878?snc=20641

TEGAL RECEIVES REPEAT ORDER FOR TEGAL 3200 SE SILICON DRIE PROCESS MODULE FROM LEADING COMMERCIAL MEMS IMAGE SENSOR MAKER

Added silicon DRIE capacity on customer's existing Tegal 3200 SE cluster tool supports High Volume Manufacturing production ramp

PETALUMA, Calif., November 04, 2010—Tegal Corporation, (Nasdaq: TGAL) an innovator of specialized production solutions for the fabrication of advanced MEMS, power ICs and optoelectronic devices, today announced it has received an order for an additional Tegal 3200 SE™ DRIE cluster tool process module from a leading supplier of MEMS image sensors. The Tegal 3200 SE DRIE process module will be shipped and installed at the customer's site in early CY2011, and will support the customer's plans for quickly ramping production capacity for High Volume Manufacturing of MEMS image sensors.

The Tegal 3200 SE cluster tool silicon DRIE process module order from this repeat Tegal DRIE customer follows the successful installation, process qualification, and sustained use of silicon Deep Reactive Ion Etch processes on the customer's first Tegal 3200 SE cluster tool PM.

Silicon DRIE for the TSV Age Webinar

---------- Forwarded message ----------
From: **MEMS Investor Journal** <editor@memsinvestorjournal.com>
Date: Tue, Nov 2, 2010 at 9:01 PM
Subject: Webinar: Silicon DRIE for the TSV Age
To: pwerbane@tegal.com

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Webinar Announcement:
Silicon DRIE for the TSV Age

Topics will include:
* 3D integration and Through Substrate Via perspectives – observations from Academia, commercial Compound Semiconductor fabrication, and commercial MEMS fabrication
* In-depth review of Silex Microsystems 3D – TSV solutions
* Development goals for EU IDP projects targeting commercial 3D-IC: Verdi (high-density TSV), 3Dice (mid-density TSV), and Smartstack (low-density TSV)
* Tegal silicon DRIE 3D-IC development activities and results
* Silicon DRIE for the TSV Age: future challenges

Sponsor: Tegal Corporation
Speaker: Nicolas Launay, Research and Development Director and General Manager, Tegal France
Time: Tuesday, November 9, 2010 2:00 PM - 3:00 PM EST

Register today!

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Closing Keynote Speaker

Dr. Vida Ilderem

Vice President, Intel Labs,
Director, Integrated Platform Research Lab,
Intel Corporation

Vida Ilderem is vice president of Intel Labs and director of the Integrated Platform Research Lab for Intel Corporation. The research lab focuses on deep integration on highly integrated platform-on-chip architectures as well as digital, analog and physical design factors.

Prior to joining Intel, Ilderem served as vice president of Systems and Technology Research at Motorola's Applied Research and Technology Center where she led research efforts that focused on delivering solutions for the next generation of communication and interaction technologies and integrated systems. She has also held the position of vice president of Physical & Digital Realization with focus on visual, computational and physical technologies, and served as director of RF/IF silicon technologies within Motorola's Semiconductor Products Sector.

Ilderem holds 27 issued patents and has been featured in numerous publications. She is a recipient of the Motorola's Distinguished Innovator Award. Ilderem holds a bachelor's degrees in electrical engineering and physics from Fresno State and a master's degree and doctorate degree in electrical engineering from the Massachusetts Institute of Technology (MIT).

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